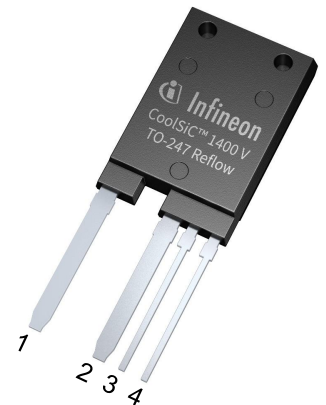


Final datasheet

CoolSiC™ 1400 V SiC MOSFET G2 : Silicon Carbide MOSFET with .XT interconnection technology

Features

- $V_{DSS} = 1400\text{ V}$ at $T_{vj} = 25^\circ\text{C}$
- $I_{DC} = 188\text{ A}$ at $T_C = 100^\circ\text{C}$
- $R_{DS(on)} = 5.8\text{ m}\Omega$ at $V_{GS} = 18\text{ V}$, $T_{vj} = 25^\circ\text{C}$
- Very low switching losses
- Package backside suitable for reflow soldering at 260°C , 3 times
- Overload operation up to $T_{vj} = 200^\circ\text{C}$
- Short circuit withstand time $2\ \mu\text{s}$
- Benchmark gate threshold voltage, $V_{GS(th)} = 4.2\text{ V}$
- Robust against parasitic turn on, 0 V turn-off gate voltage can be applied
- Robust body diode for hard commutation
- .XT interconnection technology for best-in-class thermal performance
- Wide power pins (2 mm) for high current capability
- Resistive weldable pins for direct busbar connections
- TO247PLUS package with high creepage distance 10.8 mm and $CTI \geq 600\text{ V}$
- Suitable Infineon gate drivers can be found under <https://www.infineon.com/gdfinder>



- Halogen-free
- Green
- Lead-free
- RoHS

Potential applications

- Commercial, construction and agricultural vehicles (CAV)
- EV Charging
- Online UPS / Industrial UPS
- String inverter
- Energy storage systems (ESS)
- General purpose drives (GPD)

Product validation

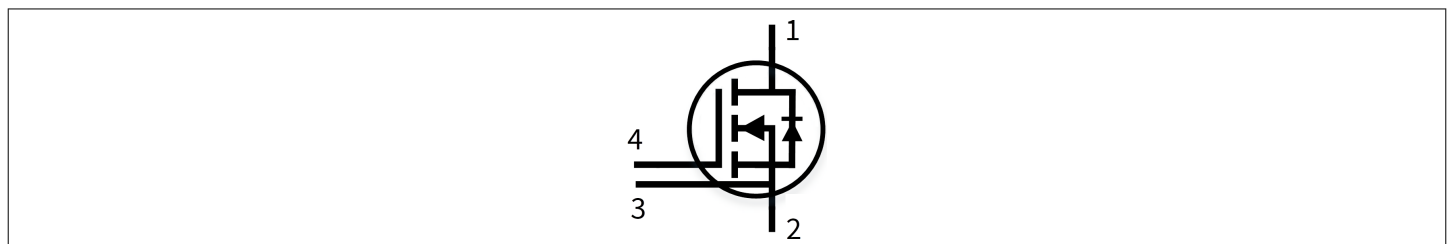
- Qualified for industrial applications according to the relevant tests of JEDEC47/20/22

Description

Pin definition:

- 1 – Drain
- 2 – Source
- 3 – Kelvin sense contact
- 4 – Gate

Note: the source and sense pins are not exchangeable, their exchange might lead to malfunction



Type	Package	Marking
IMYR140R006M2H	PG-TO247-4-U08	14M2H006

Table of contents

	Description	1
	Features	1
	Potential applications	1
	Product validation	1
	Table of contents	2
1	Package	3
2	MOSFET	3
3	Body diode (MOSFET)	6
4	Characteristics diagrams	8
5	Package outlines	14
6	Testing conditions	15
	Revision history	16
	Disclaimer	17

1 Package

Table 1 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Storage temperature	T_{stg}		-55		150	°C
Soldering temperature	T_{sold}	wave soldering 1.6 mm (0.063 in.) from case for 10 s			260	°C
		reflow soldering (MSL2 according to JEDEC J-STD-020)			260	
Thermal resistance, junction-ambient	$R_{th(j-a)}$				62	K/W
MOSFET/body diode thermal resistance, junction-case	$R_{th(j-c)}$			0.12	0.15	K/W
Comparative Tracking Index	CTI		600			V

2 MOSFET

Table 2 Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit	
Drain-source voltage	V_{DSS}	$T_{vj} \geq 25\text{ °C}$	1400	V	
Continuous DC drain current for $R_{th(j-c,max)}$, limited by $T_{vj(max)}$	I_{DDC}	$V_{GS} = 18\text{ V}$	$T_c = 25\text{ °C}$	246	A
			$T_c = 100\text{ °C}$	188	
Peak drain current, t_p limited by $T_{vj(max)}$ ¹⁾	I_{DM}	$V_{GS} = 18\text{ V}$	564	A	
Gate-source voltage, max. transient voltage	V_{GS}	$t_p \leq 0.5\ \mu\text{s}, D < 0.01$	-10...25	V	
Gate-source voltage, max. static voltage ²⁾	V_{GS}		-7...23	V	
Avalanche energy, single pulse	E_{AS}	$I_D = 138.2\text{ A}, V_{DD} = 50\text{ V}, L = 0.2\text{ mH}, T_{vj(start)} = 25\text{ °C}$	865	mJ	
Avalanche energy, repetitive	E_{AR}	$I_D = 138.2\text{ A}, V_{DD} = 50\text{ V}, L = 0.9\ \mu\text{H}, T_{vj(start)} = 25\text{ °C}$	4.3	mJ	
Short-circuit withstand time	t_{SC}	$V_{DD} \leq 800\text{ V}, V_{DS,peak} < 1400\text{ V}, V_{GS(on)} = 15\text{ V}, T_{vj(start)} = 25\text{ °C}$	2	μs	
Power dissipation, limited by $T_{vj(max)}$	P_{tot}	$T_c = 25\text{ °C}$	974	W	
		$T_c = 100\text{ °C}$	487		

1) Verified by design

2) The maximum gate-source voltage in the application design should be in accordance to IPC-9592B.

Table 3 Recommended values

Parameter	Symbol	Note or test condition	Values	Unit
Recommended turn-on gate voltage	$V_{GS(on)}$		15...18	V
Recommended turn-off gate voltage	$V_{GS(off)}$		-5...0	V

Table 4 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit	
			Min.	Typ.	Max.		
Drain-source on-state resistance	$R_{DS(on)}$	$I_D = 138.2 \text{ A}$	$T_{vj} = 25 \text{ °C}$, $V_{GS(on)} = 18 \text{ V}$		5.8		mΩ
			$T_{vj} = 150 \text{ °C}$, $V_{GS(on)} = 18 \text{ V}$		12	15.7	
			$T_{vj} = 175 \text{ °C}$, $V_{GS(on)} = 18 \text{ V}$		14		
			$T_{vj} = 25 \text{ °C}$, $V_{GS(on)} = 15 \text{ V}$		7		
Gate-source threshold voltage	$V_{GS(th)}$	$I_D = 43.5 \text{ mA}$, $V_{DS} = V_{GS}$ (tested after 1 ms pulse at $V_{GS} = 20 \text{ V}$)	$T_{vj} = 25 \text{ °C}$	3.5	4.2	5.1	V
			$T_{vj} = 175 \text{ °C}$		3.2		
Zero gate-voltage drain current	I_{DSS}	$V_{DS} = 1400 \text{ V}$, $V_{GS} = 0 \text{ V}$	$T_{vj} = 25 \text{ °C}$			1030	μA
			$T_{vj} = 175 \text{ °C}$		17.6		
Gate leakage current	I_{GSS}	$V_{DS} = 0 \text{ V}$	$V_{GS} = 23 \text{ V}$			120	nA
			$V_{GS} = -10 \text{ V}$			-120	
Forward transconductance	g_{fs}	$I_D = 138.2 \text{ A}$, $V_{DS} = 20 \text{ V}$		94		S	
Internal gate resistance	$R_{G,int}$	$f = 1 \text{ MHz}$, $V_{AC} = 25 \text{ mV}$		2.3		Ω	
Input capacitance	C_{iss}	$V_{DS} = 1000 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 100 \text{ kHz}$, $V_{AC} = 25 \text{ mV}$		9590		pF	
Output capacitance	C_{oss}	$V_{DS} = 1000 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 100 \text{ kHz}$, $V_{AC} = 25 \text{ mV}$		336		pF	
Reverse transfer capacitance	C_{rss}	$V_{DS} = 1000 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 100 \text{ kHz}$, $V_{AC} = 25 \text{ mV}$		31		pF	
C_{oss} stored energy	E_{oss}	$V_{DS} = 1000 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 100 \text{ kHz}$, $V_{AC} = 25 \text{ mV}$, Calculated based on C_{oss}		213		μJ	
Output charge	Q_{oss}	$V_{DS} = 1000 \text{ V}$, $V_{GS} = 0 \text{ V}$, Calculated based on C_{oss}		588		nC	
Effective output capacitance, energy related	$C_{o(er)}$	$V_{DS} = 0...1000 \text{ V}$, $V_{GS} = 0 \text{ V}$		666		pF	

(table continues...)

Table 4 (continued) Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Effective output capacitance, time related	$C_{o(tr)}$	$I_D = \text{constant}, V_{DS} = 0 \dots 1000 \text{ V}, V_{GS} = 0 \text{ V}$		735		pF
Total gate charge	Q_G	$V_{DD} = 1000 \text{ V}, I_D = 138.2 \text{ A}, V_{GS} = 0/18 \text{ V}, \text{turn-on pulse}$		302		nC
Plateau gate charge	$Q_{GS(pl)}$	$V_{DD} = 1000 \text{ V}, I_D = 138.2 \text{ A}, V_{GS} = 0/18 \text{ V}, \text{turn-on pulse}$		100		nC
Gate-to-drain charge	Q_{GD}	$V_{DD} = 1000 \text{ V}, I_D = 138.2 \text{ A}, V_{GS} = 0/18 \text{ V}, \text{turn-on pulse}$		60		nC
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 1000 \text{ V}, I_D = 138.2 \text{ A}, V_{GS} = 0/18 \text{ V}, R_{GS(on)} = 2.3 \Omega, R_{GS(off)} = 2.3 \Omega, L_\sigma = 12 \text{ nH}, \text{diode: body diode at } V_{GS} = 0 \text{ V}$	$T_{vj} = 25 \text{ }^\circ\text{C}$	31		ns
			$T_{vj} = 175 \text{ }^\circ\text{C}$	27		
Rise time	t_r	$V_{DD} = 1000 \text{ V}, I_D = 138.2 \text{ A}, V_{GS} = 0/18 \text{ V}, R_{GS(on)} = 2.3 \Omega, R_{GS(off)} = 2.3 \Omega, L_\sigma = 12 \text{ nH}, \text{diode: body diode at } V_{GS} = 0 \text{ V}$	$T_{vj} = 25 \text{ }^\circ\text{C}$	17		ns
			$T_{vj} = 175 \text{ }^\circ\text{C}$	16		
Turn-off delay time	$t_{d(off)}$	$V_{DD} = 1000 \text{ V}, I_D = 138.2 \text{ A}, V_{GS} = 0/18 \text{ V}, R_{GS(on)} = 2.3 \Omega, R_{GS(off)} = 2.3 \Omega, L_\sigma = 12 \text{ nH}, \text{diode: body diode at } V_{GS} = 0 \text{ V}$	$T_{vj} = 25 \text{ }^\circ\text{C}$	73		ns
			$T_{vj} = 175 \text{ }^\circ\text{C}$	80		
Fall time	t_f	$V_{DD} = 1000 \text{ V}, I_D = 138.2 \text{ A}, V_{GS} = 0/18 \text{ V}, R_{GS(on)} = 2.3 \Omega, R_{GS(off)} = 2.3 \Omega, L_\sigma = 12 \text{ nH}, \text{diode: body diode at } V_{GS} = 0 \text{ V}$	$T_{vj} = 25 \text{ }^\circ\text{C}$	31		ns
			$T_{vj} = 175 \text{ }^\circ\text{C}$	34		
Turn-on energy	E_{on}	$V_{DD} = 1000 \text{ V}, I_D = 138.2 \text{ A}, V_{GS} = 0/18 \text{ V}, R_{GS(on)} = 2.3 \Omega, R_{GS(off)} = 2.3 \Omega, L_\sigma = 12 \text{ nH}, \text{diode: body diode at } V_{GS} = 0 \text{ V}$	$T_{vj} = 25 \text{ }^\circ\text{C}$	4040		μJ
			$T_{vj} = 175 \text{ }^\circ\text{C}$	6010		

(table continues...)

3 Body diode (MOSFET)

Table 4 (continued) Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Turn-off energy	E_{off}	$V_{DD} = 1000\text{ V}$, $I_D = 138.2\text{ A}$, $V_{GS} = 0/18\text{ V}$, $R_{GS(on)} = 2.3\ \Omega$, $R_{GS(off)} = 2.3\ \Omega$, $L_\sigma = 12\text{ nH}$, diode: body diode at $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ °C}$		2950	μJ
			$T_{vj} = 175\text{ °C}$		3400	
Total switching energy ¹⁾	E_{tot}	$V_{DD} = 1000\text{ V}$, $I_D = 138.2\text{ A}$, $V_{GS} = 0/18\text{ V}$, $R_{GS(on)} = 2.3\ \Omega$, $R_{GS(off)} = 2.3\ \Omega$, $L_\sigma = 12\text{ nH}$, diode: body diode at $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ °C}$		7820	μJ
			$T_{vj} = 175\text{ °C}$		12100	
Virtual junction temperature	T_{vj}		-55		175	$^{\circ}\text{C}$
Virtual junction temperature	$T_{vj(over)}$	overload, cumulative max. 100 h ²⁾			200	$^{\circ}\text{C}$

1) including E_{fr}

2) up to 5000 cycles. Maximum ΔT limited to 100 K.

Note: The chip technology was characterized up to 200 kV/ μs . The measured dV/dt was limited by measurement test setup and package.

Characteristics at $T_{vj} = 25\text{ °C}$, unless otherwise specified.

3 Body diode (MOSFET)

Table 5 Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit
Drain-source voltage	V_{DSS}	$T_{vj} \geq 25\text{ °C}$	1400	V
Peak reverse drain current, t_p limited by $T_{vj(max)}$	I_{SM}	$V_{GS} = 0\text{ V}$	564	A

Table 6 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Drain-source reverse voltage	V_{SD}	$I_{SD} = 138.2\text{ A}$, $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ °C}$		4.2	V
			$T_{vj} = 100\text{ °C}$		4.11	
			$T_{vj} = 175\text{ °C}$		4.05	

(table continues...)

Table 6 (continued) Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
MOSFET forward recovery charge	Q_{fr}	$V_{DD} = 1000\text{ V}$, $I_{SD} = 138.2\text{ A}$, $V_{GS} = 0\text{ V}$, $-di_{SD}/dt = 1000\text{ A}/\mu\text{s}$, Q_{fr} includes also Q_C	$T_{vj} = 25\text{ °C}$	0.22		μC
			$T_{vj} = 175\text{ °C}$	3.08		
MOSFET peak forward recovery current	I_{frm}	$V_{DD} = 1000\text{ V}$, $I_{SD} = 138.2\text{ A}$, $V_{GS} = 0\text{ V}$, $-di_{SD}/dt = 1000\text{ A}/\mu\text{s}$, Q_{fr} includes also Q_C	$T_{vj} = 25\text{ °C}$	21		A
			$T_{vj} = 175\text{ °C}$	37		
MOSFET forward recovery energy	E_{fr}	$V_{DD} = 1000\text{ V}$, $I_{SD} = 138.2\text{ A}$, $V_{GS} = 0\text{ V}$, $-di_{SD}/dt = 1000\text{ A}/\mu\text{s}$, Q_{fr} includes also Q_C	$T_{vj} = 25\text{ °C}$	830		μJ
			$T_{vj} = 175\text{ °C}$	2700		
Virtual junction temperature	T_{vj}		-55		175	$^{\circ}\text{C}$
Virtual junction temperature	$T_{vj(over)}$	overload, cumulative max. 100 h ¹⁾			200	$^{\circ}\text{C}$

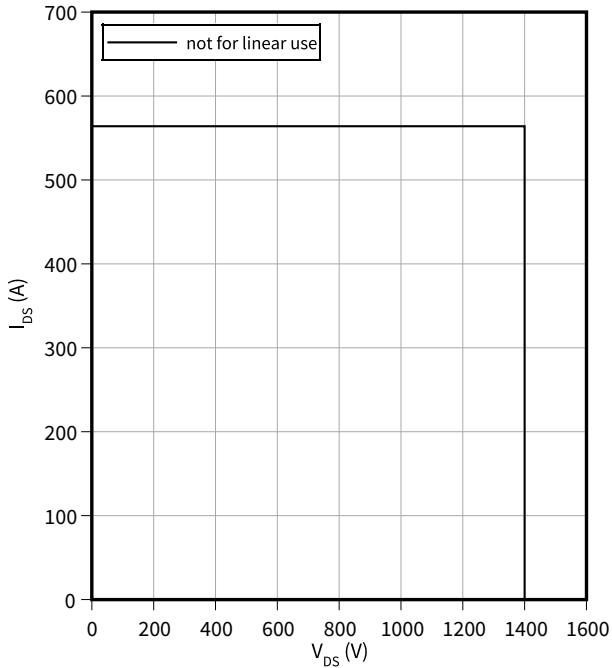
1) up to 5000 cycles. Maximum ΔT limited to 100 K.

4 Characteristics diagrams

Reverse bias safe operating area (RBSOA)

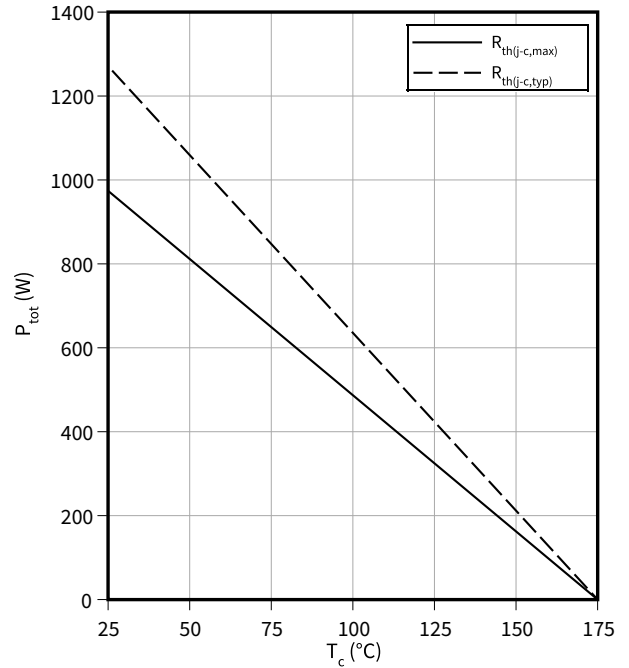
$$I_{DS} = f(V_{DS})$$

$$T_{vj} \leq 200 \text{ }^\circ\text{C}, V_{GS} = 0/18 \text{ V}, T_c = 25 \text{ }^\circ\text{C}$$



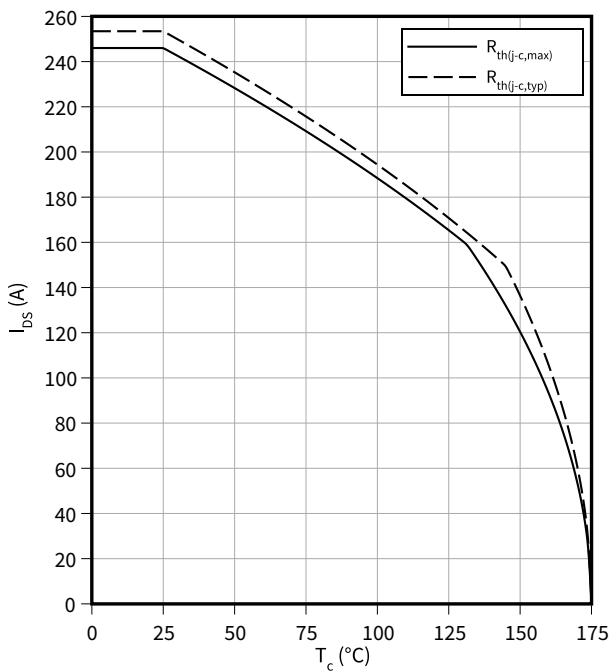
Power dissipation as a function of case temperature limited by bond wire

$$P_{tot} = f(T_c)$$



Maximum DC drain to source current as a function of case temperature limited by bond wire

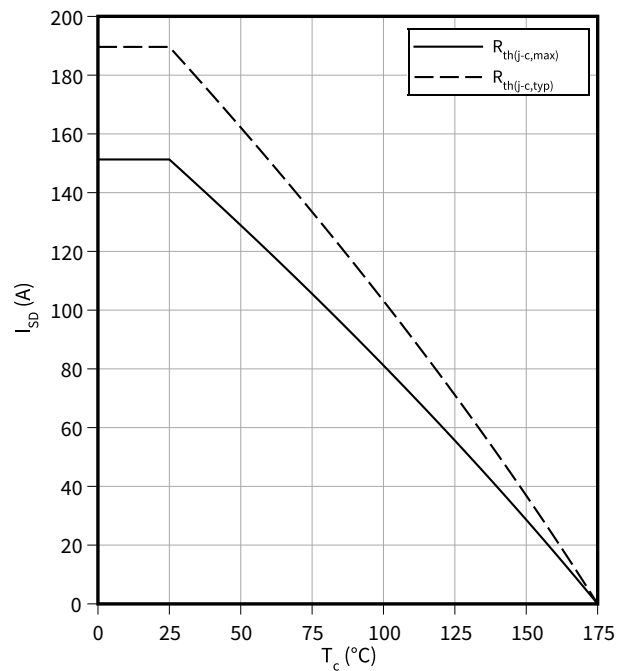
$$I_{DS} = f(T_c)$$



Maximum source to drain current as a function of case temperature limited by bond wire

$$I_{SD} = f(T_c)$$

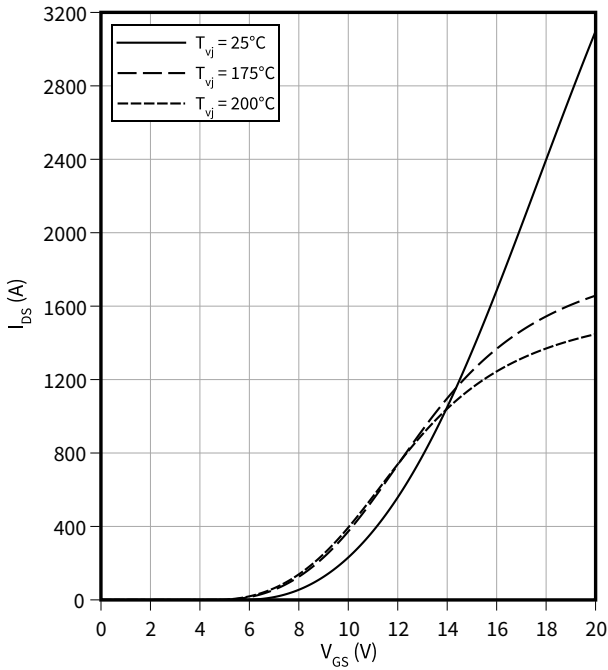
$$V_{GS} = 0 \text{ V}$$



4 Characteristics diagrams

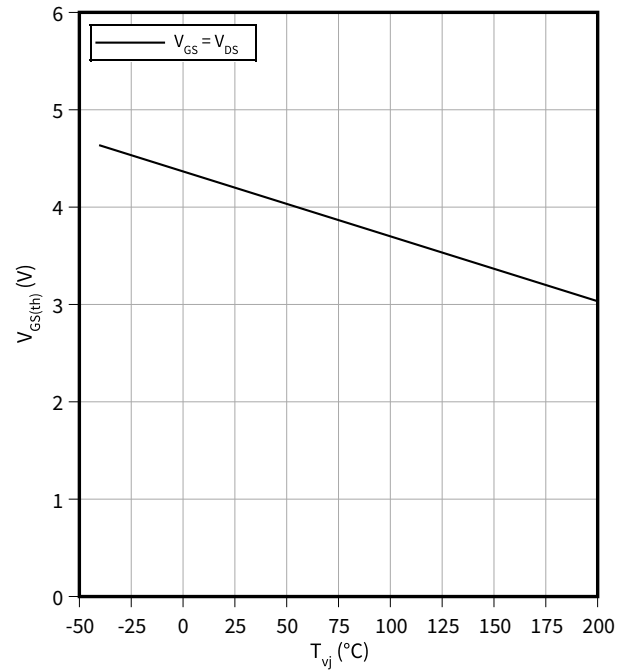
Typical transfer characteristic

$I_{DS} = f(V_{GS})$
 $V_{DS} = 20 \text{ V}$, $t_p = 20 \mu\text{s}$



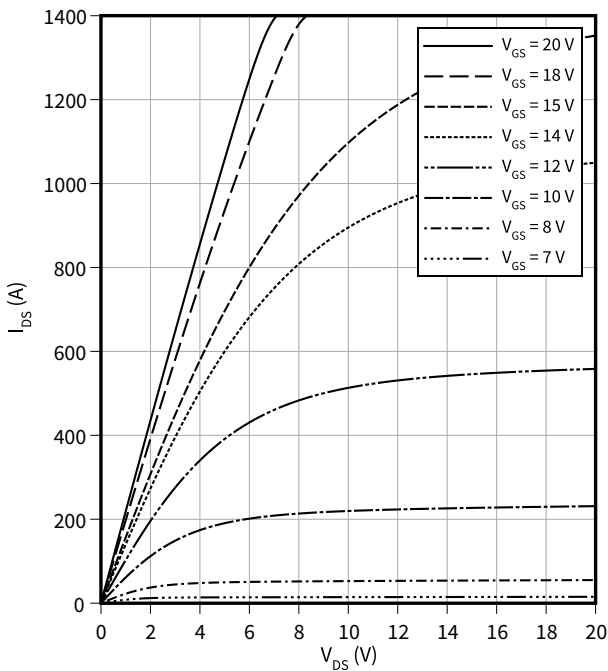
Typical gate-source threshold voltage as a function of junction temperature

$V_{GS(th)} = f(T_{vj})$
 $I_D = 43.5 \text{ mA}$



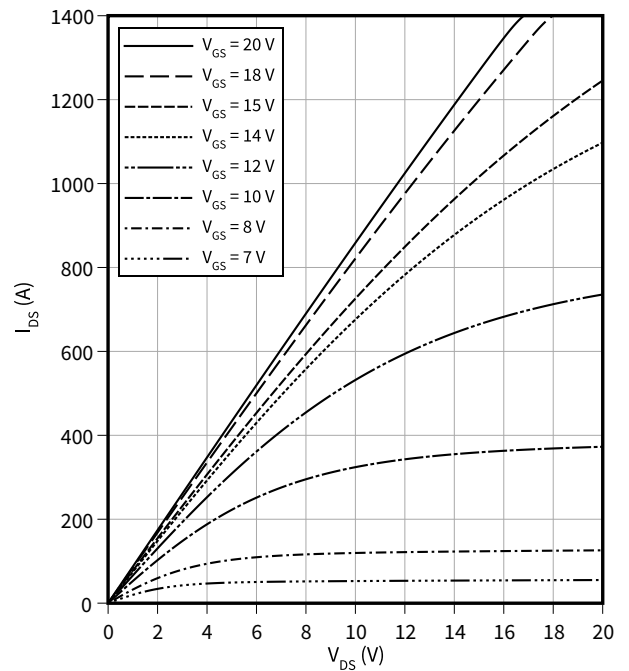
Typical output characteristic, V_{GS} as a parameter

$I_{DS} = f(V_{DS})$
 $T_{vj} = 25^\circ\text{C}$, $t_p = 20 \mu\text{s}$



Typical output characteristic, V_{GS} as a parameter

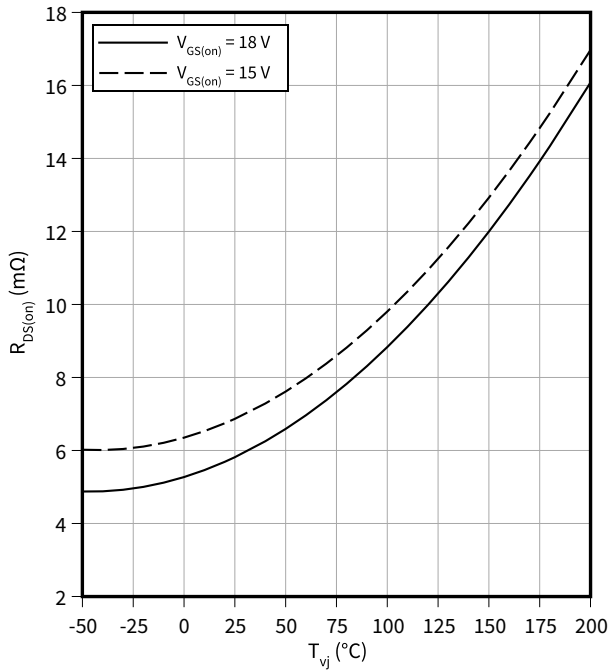
$I_{DS} = f(V_{DS})$
 $T_{vj} = 175^\circ\text{C}$, $t_p = 20 \mu\text{s}$



4 Characteristics diagrams

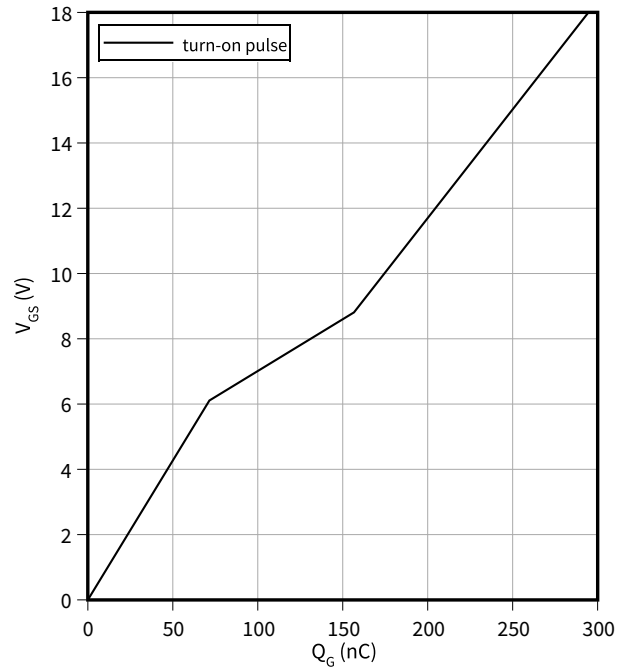
Typical on-state resistance as a function of junction temperature

$R_{DS(on)} = f(T_{vj})$
 $I_D = 138.2 \text{ A}$



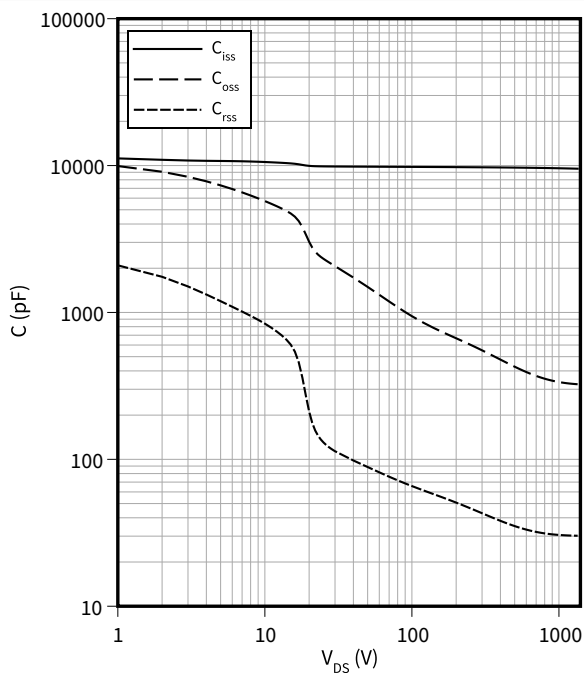
Typical gate charge

$V_{GS} = f(Q_G)$
 $I_D = 138.2 \text{ A}, V_{DS} = 1000 \text{ V}$



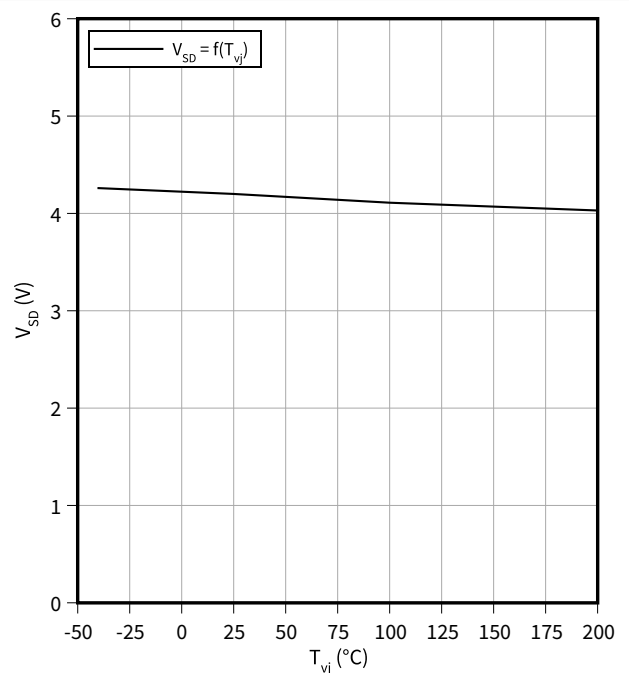
Typical capacitance as a function of drain-source voltage

$C = f(V_{DS})$
 $f = 100 \text{ kHz}, V_{GS} = 0 \text{ V}$



Typical reverse drain voltage as a function of junction temperature

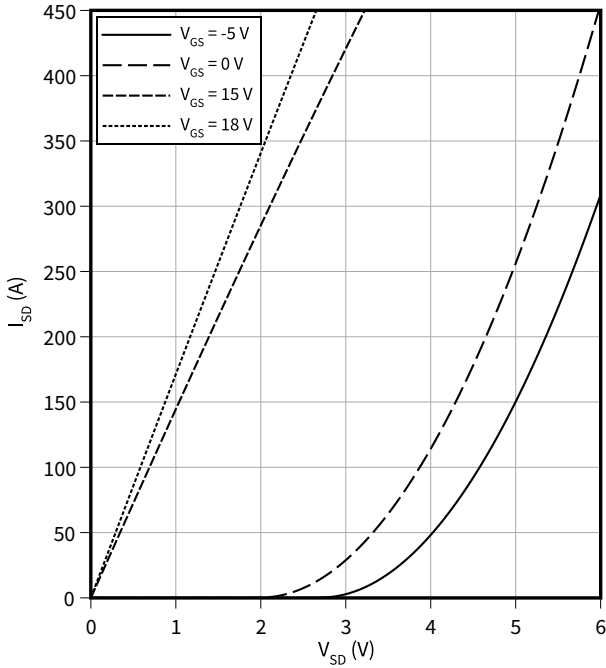
$V_{SD} = f(T_{vj})$
 $I_{SD} = 138.2 \text{ A}, V_{GS} = 0 \text{ V}$



4 Characteristics diagrams

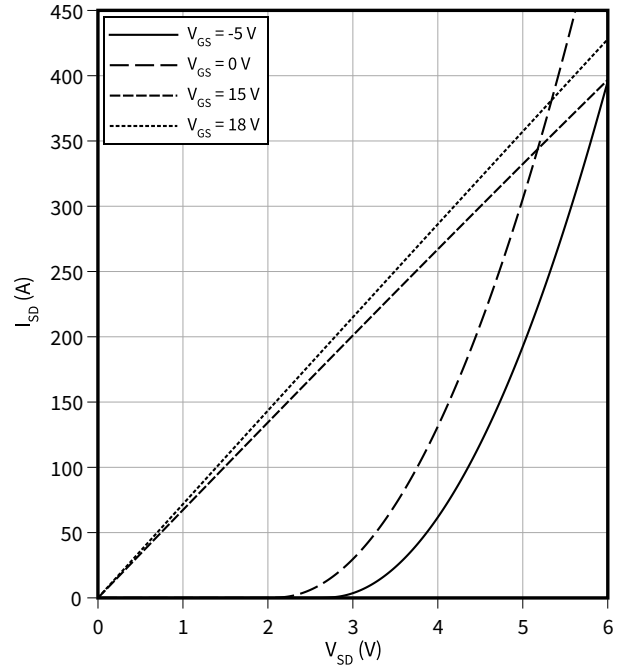
Typical reverse drain current as a function of reverse drain voltage, V_{GS} as a parameter

$I_{SD} = f(V_{SD})$
 $T_{vj} = 25\text{ °C}$, $t_p = 20\text{ }\mu\text{s}$



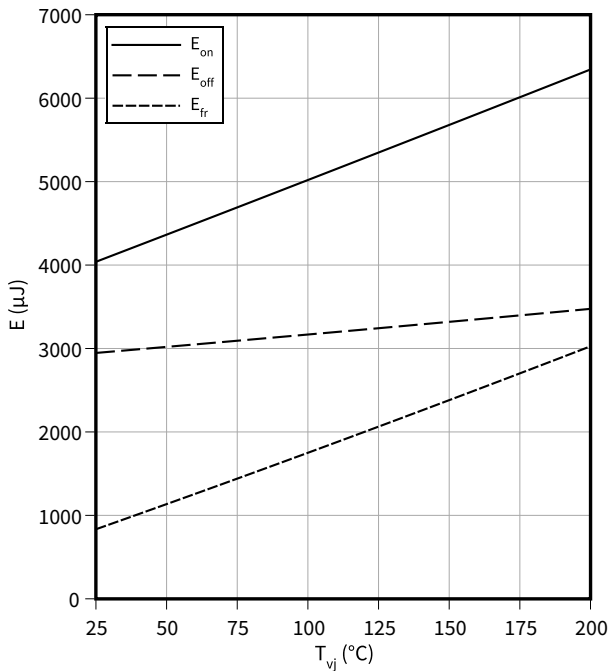
Typical reverse drain current as a function of reverse drain voltage, V_{GS} as a parameter

$I_{SD} = f(V_{SD})$
 $T_{vj} = 175\text{ °C}$, $t_p = 20\text{ }\mu\text{s}$



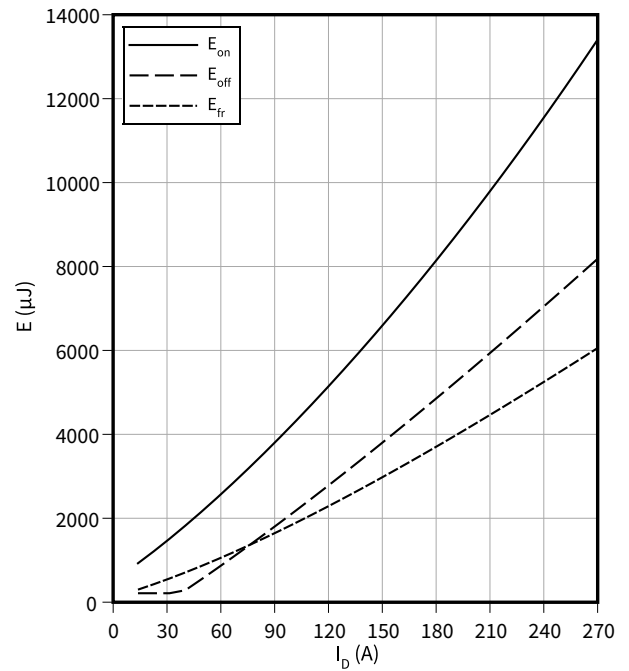
Typical switching energy as a function of junction temperature, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$E = f(T_{vj})$
 $V_{GS} = 0/18\text{ V}$, $I_D = 138.2\text{ A}$, $R_{G,ext} = 2.3\text{ }\Omega$, $V_{DD} = 1000\text{ V}$



Typical switching energy as a function of drain current, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$E = f(I_D)$
 $V_{GS} = 0/18\text{ V}$, $T_{vj} = 175\text{ °C}$, $R_{G,ext} = 2.3\text{ }\Omega$, $V_{DD} = 1000\text{ V}$

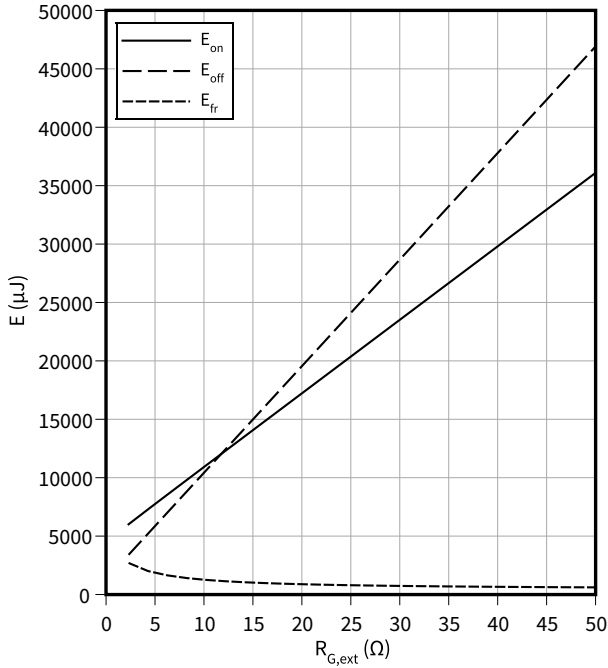


4 Characteristics diagrams

Typical switching energy as a function of gate resistance, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$E = f(R_{G,ext})$

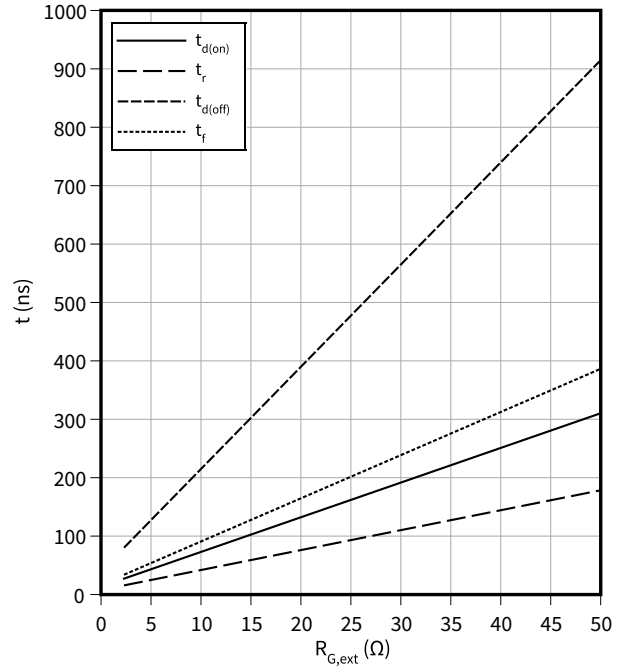
$V_{GS} = 0/18\text{ V}$, $I_D = 138.2\text{ A}$, $T_{vj} = 175\text{ °C}$, $V_{DD} = 1000\text{ V}$



Typical switching times as a function of gate resistance, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$t = f(R_{G,ext})$

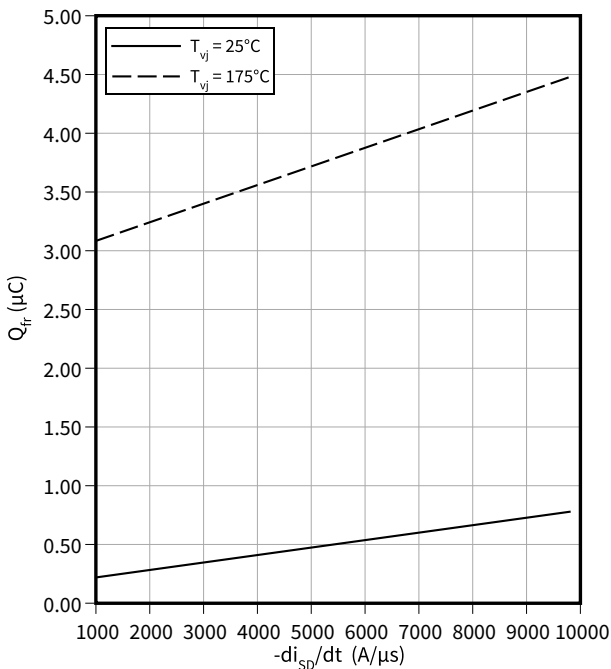
$V_{GS} = 0/18\text{ V}$, $I_D = 138.2\text{ A}$, $T_{vj} = 175\text{ °C}$, $V_{DD} = 1000\text{ V}$



Typical reverse recovery charge as a function of reverse drain current slope, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$Q_{fr} = f(-di_{SD}/dt)$

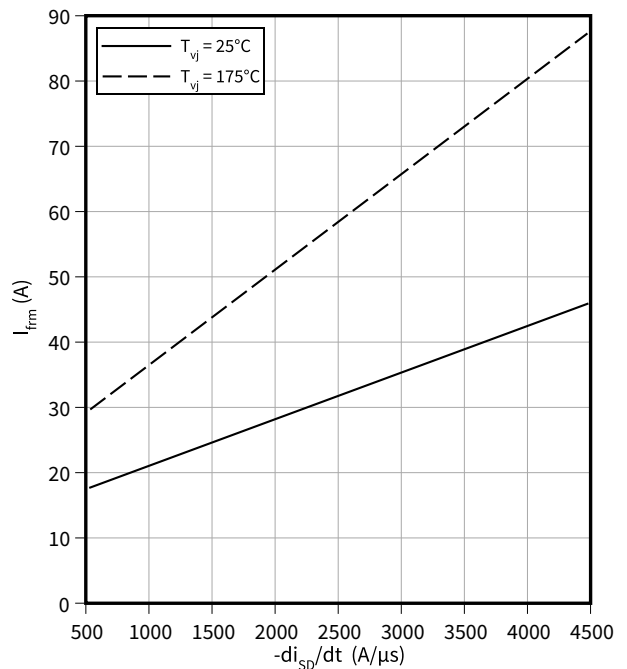
$V_{GS} = 0/18\text{ V}$, $I_{SD} = 138.2\text{ A}$, $V_{DD} = 1000\text{ V}$



Typical reverse recovery current as a function of reverse drain current slope, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$I_{frm} = f(-di_{SD}/dt)$

$V_{GS} = 0/18\text{ V}$, $I_{SD} = 138.2\text{ A}$, $V_{DD} = 1000\text{ V}$



4 Characteristics diagrams

Typical switching energy as a function of dead time / blanking time, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = -5\text{ V}$

$$E = f(t_{\text{dead}})$$

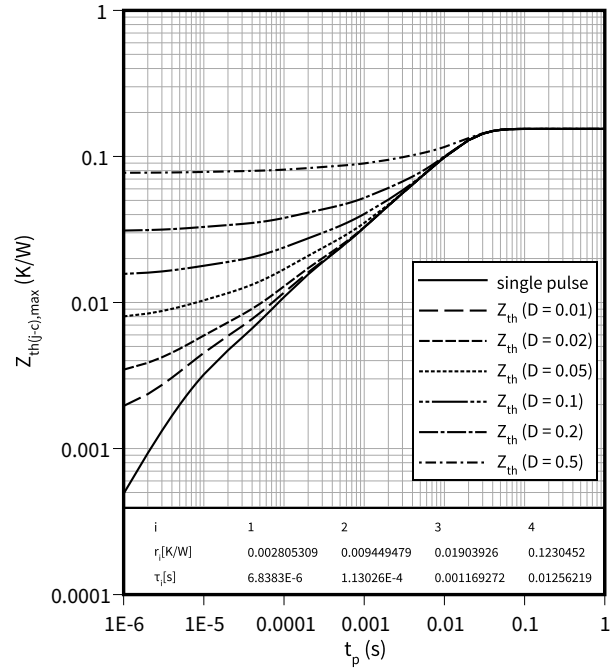
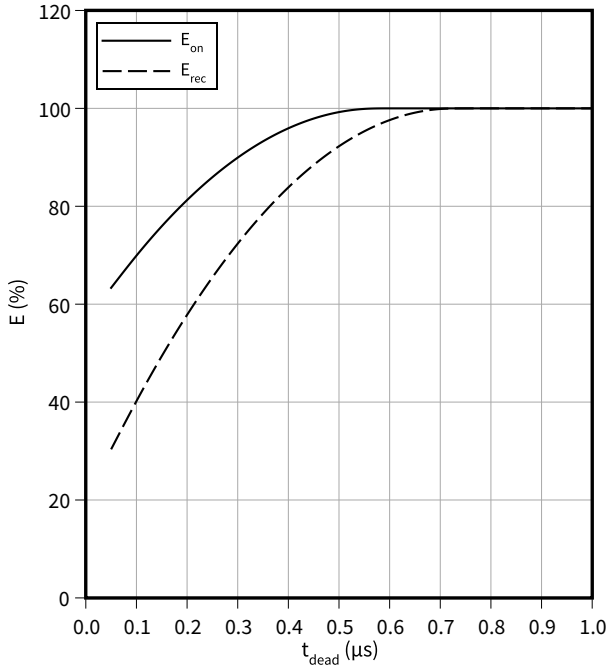
$V_{GS} = 0/18\text{ V}$, $I_D = 138.2\text{ A}$, $T_{vj} = 175\text{ °C}$, $R_{G,\text{ext}} = 2.3\text{ }\Omega$

$V_{DD} = 1000\text{ V}$

Max. transient thermal impedance (MOSFET/diode)

$$Z_{\text{th}(j-c),\text{max}} = f(t_p)$$

$$D = t_p/T$$



5 Package outlines

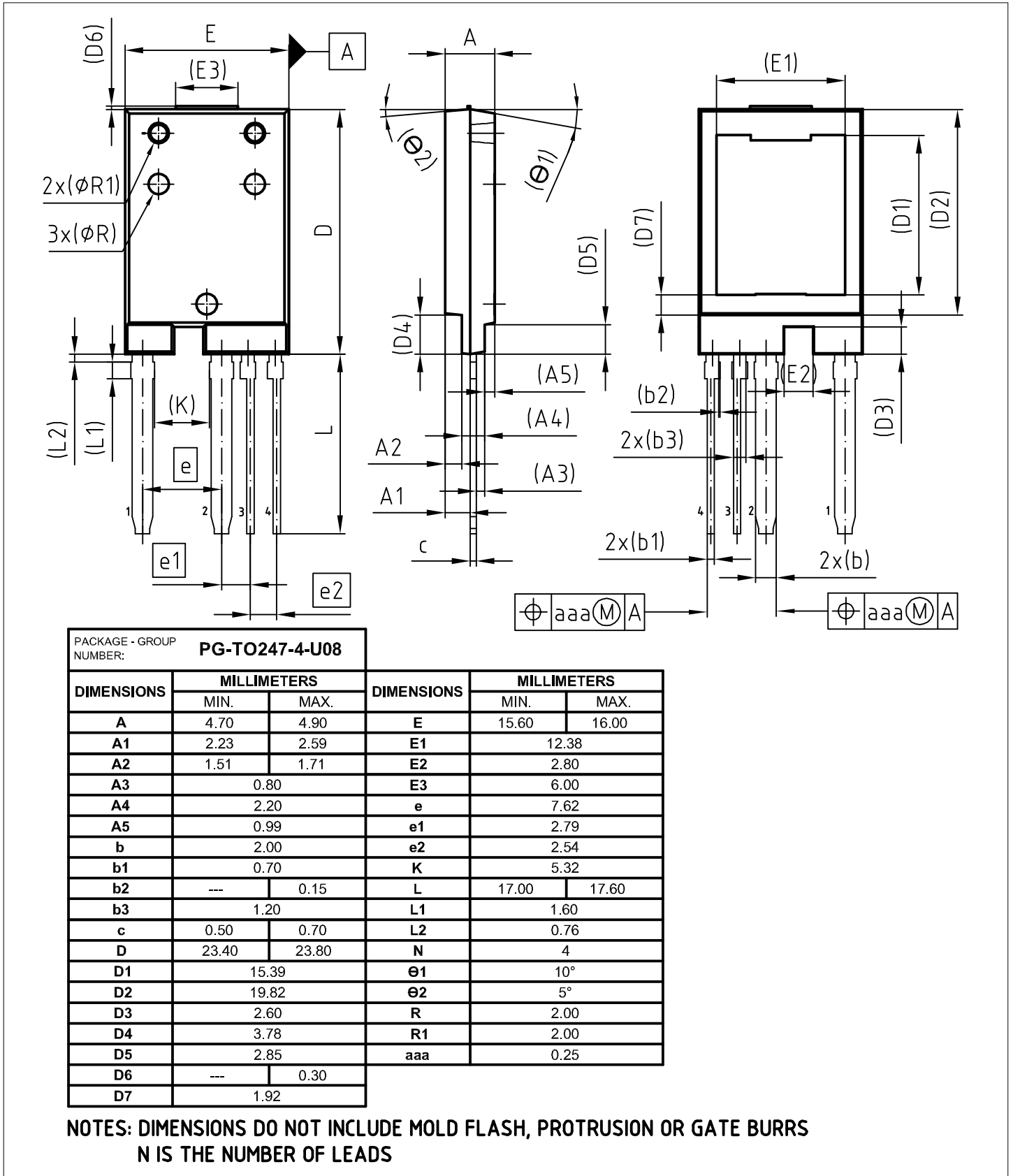


Figure 1

6 Testing conditions

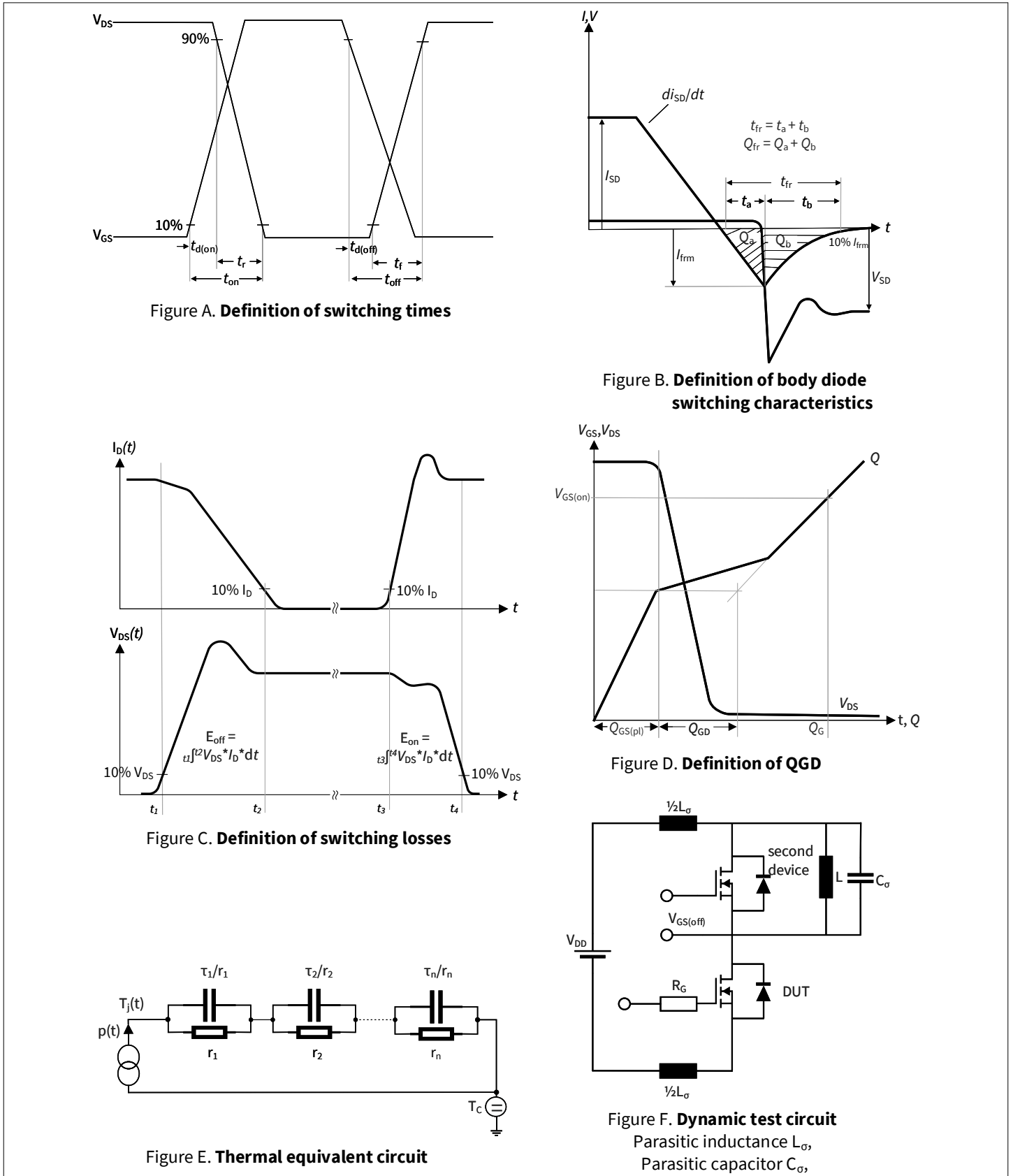


Figure 2

Revision history

Revision history

Document revision	Date of release	Description of changes
1.00	2025-02-25	Final datasheet

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